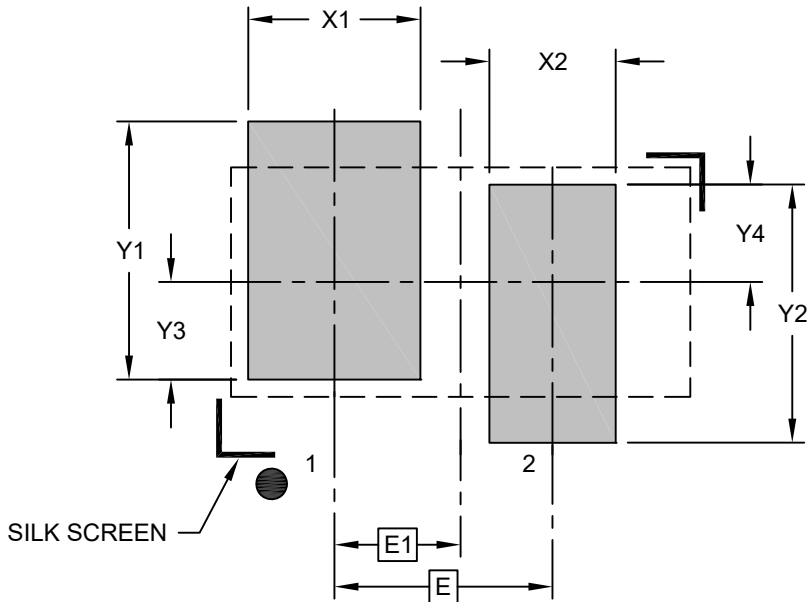


2-Lead Very Thin Single Flat, No Lead Package (LYB) - 2x4 mm Body [VSNF] Atmel Legacy Global Package Code RWX

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packageing>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		1.90 BSC		
Contact Pitch	E1		1.10 BSC		
Contact Pad Width	X1				1.50
Contact Pad Width	X2				1.10
Contact Pad Length	Y1				2.25
Contact Pad Length	Y2				2.25
Package Center to Contact Pad Edge	Y3				0.85
Package Center to Contact Pad Edge	Y4				0.85

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.